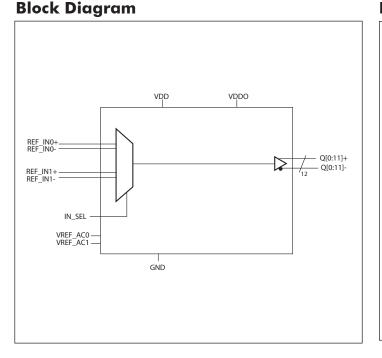




12 Output LVDS Fanout Buffer

Features

- → 12 Differential LVDS outputs
- → 2 Selectable reference inputs support either single-ended or differential
- → Up to 1.5GHz output frequency
- → Ultra low additive phase jitter: < 0.01 ps (typ) (differential 156.25MHz, 12KHz to 20MHz integration range)
- → Low skew between outputs
- → Low delay from input to output
- → Separate Input output supply voltage for level shifting
- \rightarrow 2.5V / 3.3V power supply
- → Industrial temperature support
- → TQFN-40 package



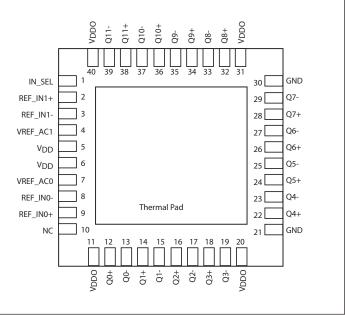
Description

The PI6C5921512 is a high performance LVDS fanout buffer device which supports up to 1.5GHz frequency. This device is ideal for systems that need to distribute low jitter LVDS clock signals to multiple destinations.

Applications

- → Networking systems including switches and Routers
- → High frequency backplane based computing and telecom platforms

Pin Configuration (40-Pin TQFN)







Pin Description

Pin #	Pin Name	T	Туре	Description
1	IN_SEL	Input	Pulldown	Input clock select. See Table 1 for function. LVCMOS/LVTTL interface levels.
2.2	REF_IN1+	T		Peference input 1 Accents Differential on Single Ended inputs
2,3	REF_IN1-		nput	Reference input 1. Accepts Differential or Single Ended inputs
4	VREF_AC1	0	utput	Bias voltage output for REF_IN1
5, 6	VDD	P	ower	Core power supply
7	VREF_AC0	0	utput	Bias voltage output for REF_IN0
<u> </u>	REF_IN0-	T		Defense es input 0. Accents Differential or Single Ended inputs
8, 9	REF_IN0+		nput	Reference input 0. Accepts Differential or Single Ended inputs
10	NC		-	No Connect
11, 20, 31, 40	VDDO	P	ower	Output power supply
12, 13	Q0+		utput	LVDS output pair 0.
12, 15	Q0-	0	utput	LVDS output pair 0.
14 15	Q1+		utput	IVDS output pair 1
14, 15	Q1-	0	utput	LVDS output pair 1.
16 17	Q2+			LVDC sutmut noin 2
16, 17	Q2-		utput	LVDS output pair 2.
10 10	Q3+			LVDC
18, 19	Q3-		utput	LVDS output pair 3.
21, 30	GND	P	ower	Power supply ground
22.22	Q4+			LVDC sutmut noin 4
22, 23	Q4-	0	utput	LVDS output pair 4.
24.25	Q5+			LVDC sutput pair 5
24, 25	Q5-		utput	LVDS output pair 5.
26.27	Q6+	0		IVDC
26, 27	Q6-		utput	LVDS output pair 6.
28.20	Q7+		utput	LVDS output pair 7
28, 29	Q7-		utput	LVDS output pair 7.
22.22	Q8+			LVDC sutmut noin 9
32, 33	Q8-		utput	LVDS output pair 8.
24.25	Q9+			
34, 35	Q9-		utput	LVDS output pair 9.
24.25	Q10+	-		
36, 37	Q10-	0	utput	LVDS output pair 10.





Pin Description Cont.

Pin #	Pin Name	Туре	Description		
29.20	Q11+	Outmut			
38, 39	Q11-	Output	LVDS output pair 11.		
Thermal pad	-	-	Thermal pad. Connect to ground.		

Function Table

Table 1: Input select function

IN_SEL	Function
0	REF_IN0 is the selected reference input
1	REF_IN1 is the selected reference input
Open	No inputs selected. Outputs Hi-Z

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
C _{IN}	Input Capcitance			2		pF
R _{PULLDOWN}	Input Pulldown Resistor			200		kΩ
R _{PULLUP}	Input Pullup Resistor			200		kΩ





Maximum Ratings (Above which the useful life may be impaired. For user guidelines, not tested)

Storage temperature55 to +150°C
Supply Voltage to Ground Potential ($V_{_{DD,}}V_{_{DDO}}$)0.5 to +4.6V
Inputs (Referenced to GND)0.5 to $\rm V_{_{\rm DD}}{+}0.5V$
Clock Output (Referenced to GND)0.5 to $\rm V_{_{\rm DD}}{+}0.5V$
Latch up200mA
ESD Protection (Input)
ESD Protection (Input) 1000 V min (CDM)

Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Power Supply Characteristics and Operating Conditions

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
37	Come Complex Welts are		3.135	3.3	3.465	V
V _{DD}	Core Supply Voltage		2.375	2.5	2.625	V
	Output Supply Voltage		3.135	3.3	3.465	V
V _{DDO}			2.375	2.5	2.625	V
I _{DD}	Core Power Supply Current			120	213	mA
I _{DDO}	Output Power Supply Current	All LVDS outputs loaded		- 120		ША
T _A	Ambient Operating Temperature		-40		85	°C

DC Electrical Specifications - Differential Inputs

Symbol	Parameter		Min.	Тур.	Max.	Units
I _{IH}	Input High current	Input = V _{DD}			20	uA
I _{IL}	Input Low current	Input = GND	-20			uA
V _{IH}	Input high voltage				V _{DD} +0.3	V
V _{IL}	Input low voltage		-0.3			V
V _{ID}	Input Differential Amplitude PK-PK		0.1			V
V _{CM}	Common model input voltage		GND + 0.5		V _{DD} -0.85	V
ISO _{MUX}	MUX isolation			-89		dBc





DC Electrical Specifications - LVCMOS Inputs

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
I _{IH}	Input High current	Input = V_{DD}			150	uA
I _{IL}	Input Low current	Input = GND	-150			uA
V _{IH}	Input high voltage	V _{DD} =3.3V	2.0		V _{DD} +0.3	V
		V _{DD} =2.5V	1.7		V _{DD} +0.3	V
V _{IL}	Input low voltage	V _{DD} =3.3V	-0.3		0.8	V
		V _{DD} =2.5V	-0.3		0.7	V

DC Electrical Specifications- LVDS Outputs

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
V _{OH}	Output High voltage			1.4		V
V _{OL}	Output Low voltage			1.0		V
37	Differential output voltage	@800MHz to ≤1.5GHz	200		400	mV
V _{OD}		@ ≤800MHz	250		450	mV
DV _{OD}	Change in V _{OD} between complete- ly output states		-50		50	mV
Vocm	Output commode voltage			1.25		V
DVocm	Change in Vocm between com- pletely output states				50	mV

AC Electrical Specifications – Differential Inputs

Parameter	Description	Conditions	Min.	Тур.	Max.	Units
FIN	Clock input frequency				1500	MHz
V _{INPP}	Differential Input peak to peak voltage	$1.5 \text{GHz} \le \text{F}_{IN} \le 2 \text{ GHz}$	0.2		1.5	V
		$F_{IN} \le 1.5 \text{ GHz}$	0.1		1.5	V
ER	Input Edge Rate		1.5			V/ns





AC Electrical Specifications – LVCMOS Inputs

Parameter	Description	Conditions	Min.	Тур.	Max.	Units
F _{IN}	Clock input frequency				200	MHz
ER	Input Edge Rate		1.5			V/ns

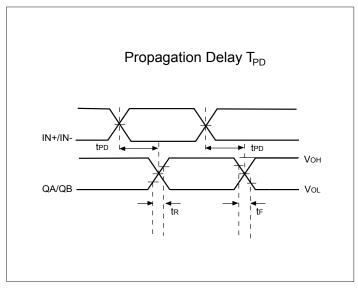
AC Electrical Specifications – LVDS Outputs

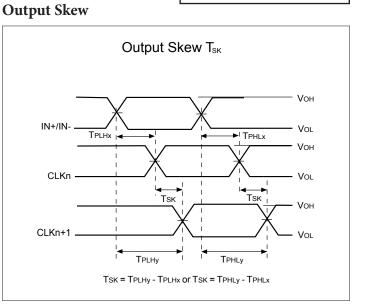
Parameter	Description	Conditions	Min.	Тур.	Max.	Units
F _{OUT}	Clock output frequency	LVDS			1500	MHz
Tr	Output rise time	From 20% to 80%		150		ps
T _f	Output fall time	From 80% to 20%		150		ps
T _{ODC}	Output duty cycle	<1.5GHz	48		52	%
T	Buffer additive jitter RMS	156.25MHz, 12kHz to 20MHz		0.01		ps
Тј		156.25MHz, 10kHz to 1MHz		0.01		ps
T _{SK}	Output Skew			13	30	ps
T _{PD}	Propagation Delay			620	700	ps
T _{OD}	Valid to HiZ				100	ns
T _{OE}	HiZ to valid				100	ns
T _{P2P Skew}	Part to Part Skew ¹		-50		50	ps
V _{REF_AC}	Input bias voltage	$I_{AC} = 2mA$		1.25		V



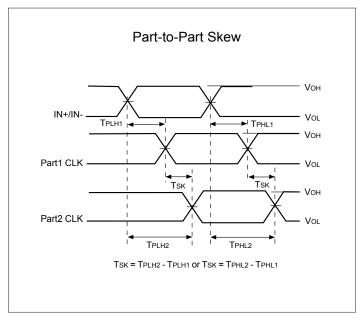


Propagation Delay



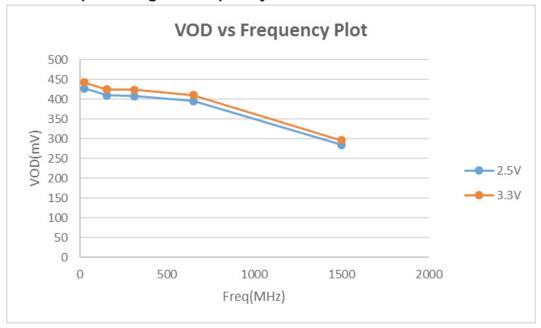


Part to Part Skew







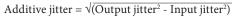


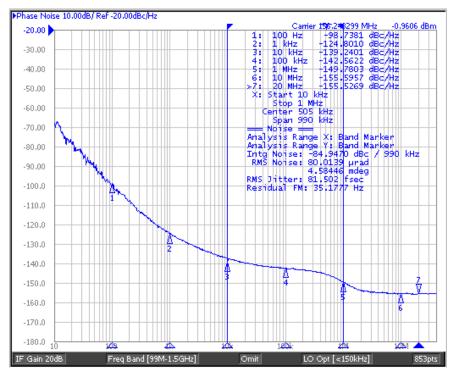
LVDS Output Swing vs. Frequency



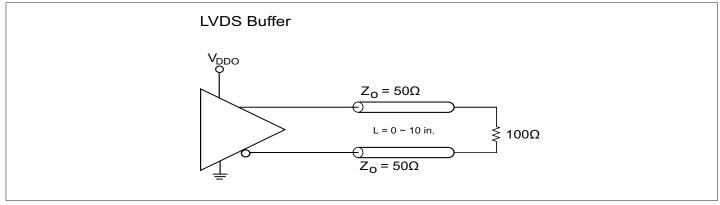


Phase Noise and Additive Jitter





Configuration Test Load Board Termination for LVDS/ LVDS Outputs





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PI6C5921512

Application Information

Wiring the differential input to accept single ended levels

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage $V_REF = V_{DD}/2$ is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to postion the V_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and $V_{DD} = 3.3V$, V_REF should be 1.25V and R1/R2 = 0.609.

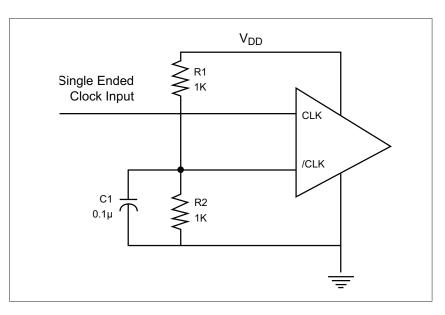
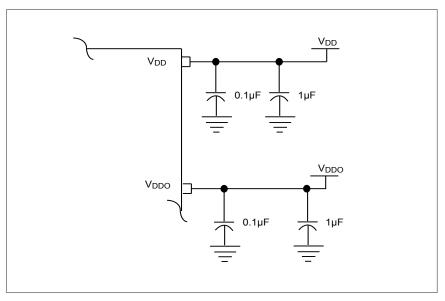


Figure 1. Single-ended input to Differential input device

Power Supply Filtering Techniques

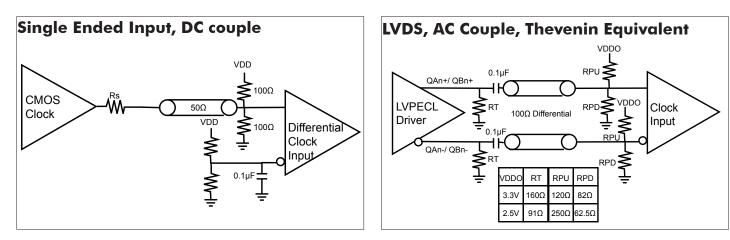
As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. All power pins should be individually connected to the power supply plane through vias, and 0.1μ F an 1μ F bypass capacitors should be used for each pin.

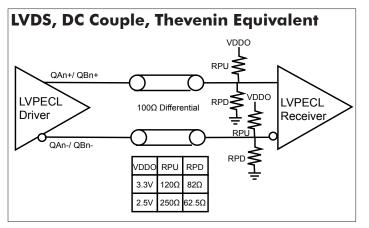


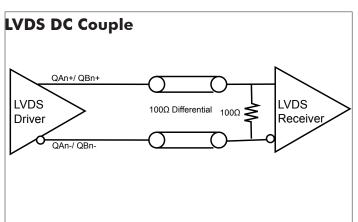


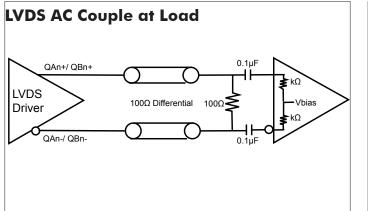
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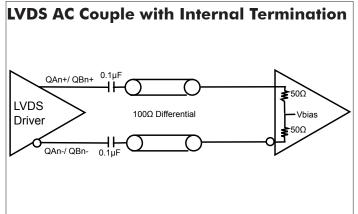
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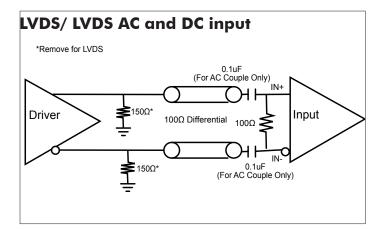






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Thermal Information

Symbol	Description	Condition	
$\Theta_{_{\mathrm{JA}}}$	Junction-to-ambient thermal resistance	Still air	26.18 °C/W
$\Theta_{\rm JC}$	Junction-to-case thermal resistance		10.52 °C/W

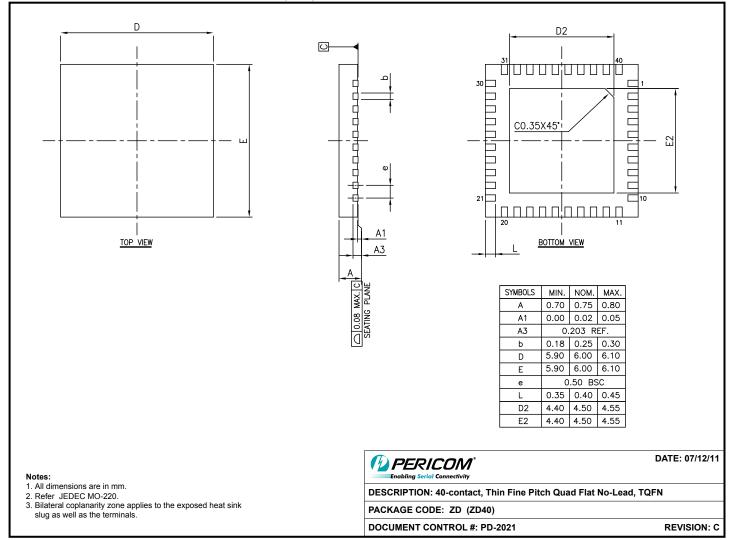
Part Marking

Top mark not available at this time. To obtain advance information regarding the top mark, please contact your local sales representative.





Packaging Mechanical: 40-TQFN (ZD)



For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Ordering Code	Package Code	Package Type	Operating Temperature
PI6C5921512ZDIEX	ZD	40-contact, Thin Fine Pitch Quad Flat No-Lead (TQFN)	-40 °C to 85 °C

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See http://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free. Thermal characteristics can be found on the company web site at www.diodes.com/design/support/packaging/

3. E = Pb-free and Green

4. X suffix = Tape/Reel





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